



Docket No.: M4065.0018/P018-A  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application of:  
Rodney C. Langley et al.

Allowed: June 8, 2004

Application No.: 09/507,465

Confirmation No.: 2423

Filed: February 22, 2000

Art Unit: 1765

For: METHOD AND APPARATUS FOR  
PLASMA ETCHING A WAFER

Examiner: M. A. Anderson

**COMMENTS ON EXAMINER'S**  
**STATEMENT OF REASONS FOR ALLOWANCE**

U.S. Patent and Trademark Office  
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Dear Sir:

Applicants agree in part with the Examiner's statement for allowance in that the prior art of record fails to disclose the limitations noted by the Examiner. However, the Examiner's statement does not reflect all of the language of each of the allowed claims. The totality of the language of each claim provides additional reasons for the allowance of each claim.

Dated: August 27, 2004

Respectfully submitted,

By 

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